

20th anniversary!

Call for Papers

ICEP 2021

2021 International Conference on Electronics Packaging

Date: May 12 - 14, 2021

Conference style: **FULL ONLINE** (Live & On-demand)

Important: ICEP 2021 has been changed to FULL ONLINE system in order to ensure epidemic prevention. DO NOT arrange a trip to JPN!

Sponsor: Japan Institute of Electronics Packaging (JIEP)
Technical Co-Sponsors: IEEE EPS Japan Chapter, iMAPS

Conference Topics & Special Notice for Authors

Conference Topic

Category 1

- Advanced Packaging
- Quality, Modeling, and Reliability

Category 2

- Interconnections
- Materials & Processing

Category 3

- Power Electronics
- Thermal Management
- Highspeed, Wireless & Components
- Emerging Technologies

Poster Presentations

- ❑ Posters will be opened online during the conference duration
- ❑ The authors will be asked to provide pre-recorded short presentations
- ❑ Live discussion opportunities will be provided to the presenters (TBD)

Oral Presentations

Oral presentations will be carried out in two ways: 1) Live and 2) On-Demand. The authors can take either way, will be asked to choose their preference on the abstract submission, can modify the choice on the acceptance notice.

Live oral presentations:

- ❑ Real-time online presentations and discussions in certain session time
- ❑ The authors will be required to submit pre-recorded presentation files for backup just in case
- ❑ Backup pre-recorded files can be opened also in the On-Demand site on the authors' requests (will be asked in the acceptance notice)

On-Demand oral presentations:

- ❑ Pre-recorded presentation videos will be opened in On-Demand site for certain duration (TBD)
- ❑ Confidentiality of the contents is on the authors
- ❑ The authors are recommended to include the contact information in the presentation to let Q&As

OUR POLICY:

1. ICEP committee does **NOT** allow to record the presentations and discussions in **ANY WAY** to secure non-commercial public interests of an international conference.
2. The authors, except for the Keynote Lecturers and Session Invited Speakers, are **required to release the copyright** of all submitted contents. For details, visit: <https://ux.nu/o27ui>



See the backside for details



Important Dates

Abstract submission open:	September 1st, 2020
Abstract deadline:	November 30th, 2020
Notification of acceptance:	January 15th, 2021
Final manuscript deadline:	March 1st, 2021

- Authors are encouraged to use the abstract template found at the conference website: <http://www.jiep.or.jp/icep/>
- Once the abstract is accepted, the authors will be required to prepare a **2-pages final paper**: For the final paper format, see: <http://www.jiep.or.jp/icep/>
- Accepted papers will be submitted for inclusion into IEEE Xplore as well as other Abstracting and Indexing (A&I) databases (EI Compendex and INSPEC).
- Authors are encouraged to submit their manuscripts to Transactions of The Japan Institute of Electronics Packaging, with enhanced contents of 4 – 10 pages. For details, please see: <https://www.jstage.jst.go.jp/browse/jiepeng/-char/en>

About ICEP

ICEP is counted as one of the largest Asian international conferences on electronic packaging, attracting more than 400 attendees and hosting over 30 technical sessions every year since 2001. This time, ICEP2021, is the 20th anniversary, being held at Miraikan, Tokyo, Japan, where the attendees will feel an “electric” atmosphere of the Olympic games.

Unfortunately, we had to cancel the last time ICEP due to worldwide COVID-19 situation. However, regarded this experience as a good opportunity to increase the choices of participation measures, ICEP 2021 will take place in FULL ONLINE system with several different choices of presentation styles for global participants.

We sincerely hope all the attendees make the most of ICEP 2021 as a cross-cutting platform to dynamize and deepen their R&D activities.

Main Sponsor: Japan Institute for Electronics Packaging (JIEP)
Technical Co-Sponsors: IEEE Electronics Packaging Society (EPS) Japan Chapter, IMAPS

Registration Fee

The details of the registration fee will be announced in the conference HP ASAP when the conference operation style is finally decided (no later than **January 2021**).

The following items are included in the registration fee: Receptions, proceedings, and **the archive of all 1st to 19th ICEP proceedings as the privilege of the 20th anniversary**. How-to-get will be announced in the homepage, too.

Outstanding Technical Paper Award

This award recognizes the outstanding papers presented at ICEP. The award will be given to the presenting author and co-authors of the selected papers.

Funding: The award is sponsored by JIEP.

Eligibility: The presenter must be listed as one of the authors. Conference papers must be submitted on or before the due date.

Basis: Papers are reviewed based on: Originality, technical contents, relevance, technical impact of the written paper, and the quality of the conference presentation.

IEEE EPS Japan Chapter Young Award

This award recognizes the excellent papers presented by young scientists and engineers at ICEP. This award will be given to the presenting author.

Funding: The award is sponsored by IEEE EPS Japan Chapter.

Eligibility: The presenter must be listed as the first author of their paper. The presenter must be younger than 35 years old on December 31 of the presentation year. Previous winners are not eligible. Conference papers must be submitted on or before the due date. The award recipient must be a member of IEEE and EPS at the time the award is received.

Basis: The basis is same as Outstanding Technical Paper Award, with different allocation of points on each item.

Organizing Committee

General Chair:

Eiji Higurashi, National Institute of Advanced Industrial Science and Technology (AIST)

General Vice Chairs:

Shigenori Aoki, LINTEC corporation

Katsuyuki Miyama, Hokkaido University of Science

Akitsu Shigetou, National Institute for Materials Science (NIMS)

Sponsorship Opportunities

The ICEP committee intends to provide cross-disciplinary support for R&D related to electronics packaging technology and is broadly recruiting sponsors who kindly support this idea. Sponsors will receive various benefits in addition to discounted fees. The detail will be announced on the conference website soon.

Contact

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URL: <http://www.jiep.or.jp/icep/>

